



Title of Change:	SOIC 14/16 Additional Assembly and Test Site with same die, die attach, wire material and size, mold compound materials, and Test as current Internal site.
Proposed Changed Material First Ship Date:	16 Jan 2022 or earlier if approved by customer
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local ON Semiconductor Sales Office or logic.fpcn@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com> . Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	N/A
PPAP Availability Date:	N/A
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Chielo.Basa@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .
Change Category	
Category	Type of Change
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Change of direct material supplier, Change of product marking
Description and Purpose:	
Qualify new subcontractor site to increase capacity for SOIC 14/16 leads. After the proposed 1 st ship date, parts will be supplied from either Philippine site. There are no product material changes as a result of this change.	
Test is performed on the same tester, test program and handler combination in both facilities.	
Note the parts in this FPCN are used as Automotive application.	



	Before Change	After Change
Assembly and Test Site	ON Semiconductor Carmona, Philippines	ON Semiconductor Carmona, Philippines or ATEC - Automated Technology, Philippines

	Existing Site	New Site
Product marking change	ASSEMBLY CODE: "P" 	ASSEMBLY CODE: "Y"  No change in marking style. The only difference is the assembly code

Reason / Motivation for Change:	Source/Supply/Capacity Changes
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.
Sites Affected:	
ON Semiconductor Sites	External Foundry/Subcon Sites
ON Semiconductor Carmona, Philippines	ATEC - Automated Technology, Philippines
Marking of Parts/ Traceability of Change:	Assembly code will be different for parts from new site

**Reliability Data Summary:****QV DEVICE NAME:** MC74HC4051ADR2G**RMS:** O48177 | O72374**PACKAGE:** SOIC 16

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C	2016 hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	2016 hrs	0/231
TC	JESD22-A104	Ta= -65°C to + 150°C	1000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		0/693
SD	JSTD002	Ta = 245C, 10 sec		0/ 45
PD	JESD22-B100 and JESD22-B108	Per Case Outline		0/30

NOTE: AEC-1pager is attached.*To view attachments:*

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file

Electrical Characteristics Summary:

Electrical characteristics Available upon request.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
NLV74HC138ADR2G	NA	MC74HC4051ADR2G
NLV74HC139ADR2G	NA	MC74HC4051ADR2G
NLV74HC151ADR2G	NA	MC74HC4051ADR2G
NLVHC4851ADR2G	NA	MC74HC4051ADR2G
NLVHC259ADR2G	NA	MC74HC4051ADR2G
NLVHC165ADR2G	NA	MC74HC4051ADR2G
NLV74HCT4851ADRG	NA	MC74HC4051ADR2G
NLV74HC595ADR2G	NA	MC74HC4051ADR2G
NLV74HC589ADR2G	NA	MC74HC4051ADR2G
NLV74HC4852ADR2G	NA	MC74HC4051ADR2G



NLV74HC4851ADR2G	NA	MC74HC4051ADR2G
NLV74HC4094BDR2G	NA	MC74HC4051ADR2G
NLV74HC4060ADR2G	NA	MC74HC4051ADR2G
NLV74HC4053ADR2G	NA	MC74HC4051ADR2G
NLV74HC4052ADR2G	NA	MC74HC4051ADR2G
NLV74HC4051ADR2G	NA	MC74HC4051ADR2G
NLV74HC4040ADR2G	NA	MC74HC4051ADR2G
NLV74HC4020ADR2G	NA	MC74HC4051ADR2G
NLV74HC390ADR2G	NA	MC74HC4051ADR2G
NLV74HC251ADR2G	NA	MC74HC4051ADR2G
NLV74HC238ADR2G	NA	MC74HC4051ADR2G
NLV74HC174ADR2G	NA	MC74HC4051ADR2G
NLV74HC165ADR2G	NA	MC74HC4051ADR2G
NLV74HC157ADR2G	NA	MC74HC4051ADR2G